162162
G00002

ABSTRACT

A semiconductor wafer bonding product according to the present invention includes: a semiconductor wafer; a transparent substrate provided at a side of a functional surface of the semiconductor wafer; a spacer provided between the semiconductor wafer and the transparent substrate; and a bonded portion continuously provided along a periphery of the semiconductor wafer, the transparent substrate being bonded to the semiconductor wafer through the bonded portion. It is preferred that a minimum width of the bonded portion is 50 μm or more.